# Bond-Ply® 400

Thermally Conductive, Un-Reinforced, Pressure Sensitive Adhesive Tape

#### **Features and Benefits**

- Thermal impedance: 0.87°C-in<sup>2</sup>/W (@50 psi)
- Easy application
- Eliminates need for external hardware (screws, clips, etc.)
- Available with easy release tabs



Bergquist Bond-Ply 400 is an un-reinforced, thermally conductive, pressure sensitive adhesive tape. The tape is supplied with protective topside tabs and a carrier liner. Bond-Ply 400 is designed to attain high bond strength to a variety of "low energy" surfaces, including many plastics, while maintaining high bond strength with long term exposure to heat and high humidity.

# Typical Applications Include:

Secure:

- Heat sink onto BGA graphic processor
- Heat sink to computer processor
- Heat sink onto drive processor
- Heat spreader onto power converter PCB
- Heat spreader onto motor control PCB

### **Configurations Available:**

 Die-cut parts (supplied on rolls with easy release, protective tabs)

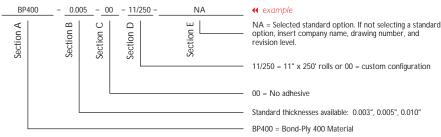
TYPICAL PROPERTIES OF BOND-PLY 400						
PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	White		White		Visual	
Thickness (inch) / (mm)	0.003 to 0.010		0.076 to 0.254		ASTM D374	
Glass Transition (°F) / (°C)	-22		-30		ASTM E1356	
Continuous Use Temp (°F) / (°C)	-22 to 248		-30 to 120		_	
ADHESION						
Lap Shear @ RT (psi) / (MPa)	100		0.7		ASTM D1002	
Lap Shear after 5 hr @ 100°C	200		1.4		ASTM D1002	
Lap Shear after 2 min @ 200°C	200		1.4		ASTM D1002	
ELECTRICAL			VALUE		TEST METHOD	
Dielectric Breakdown Voltage (Vac)			3000		ASTM D149	
Flame Rating			V-O		U.L.94	
THERMAL						
Thermal Conductivity (W/m-K)			0.4		ASTM D5470	
THERMAL PERFORMANCE vs PRESSURE						
Initial Assembly Pressure (psi for 5 seconds) 10		10	25	50	100	200
TO-220 Thermal Performance (°C/W) 0.005"		5.4	5.4	5.4	5.4	5.4
Thermal Impedance (°C-in²/W) (1)				0.87		
1) The ASTM D5470 test fixture was used The recorded value includes interfacial thermal resistance These						

1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

**Shelf Life:** The double-sided pressure sensitive adhesive used in Bond-Ply products requires the use of dual liners to protect the surfaces from contaminants. Bergquist recommends a 6-month shelf life at a maximum continuous storage temperature of 35°C, or 3-month shelf life at a maximum continuous storage temperature of 45°C, for maintenance of controlled adhesion to the liner. The shelf life of the Bond-Ply material, without consideration of liner adhesion (which is often not critical for manual assembly processing), is recommended at 12 months from date of manufacture at a maximum continuous storage temperature of 60°C.

### **Building a Part Number**

## **Standard Options**



Note: To build a part number, visit our website at www.bergquistcompany.com.

Bond-Ply®: U.S. Patent 5,090,484 and others.